

CoolMOS™ Power Transistor

Features

- Lowest figure-of-merit $R_{ON} \times Q_g$
- Extreme dv/dt rated
- High peak current capability
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant
- Ultra low gate charge

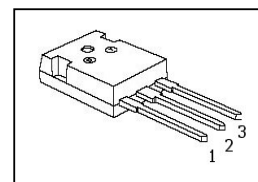
CoolMOS CP is specially designed for:

- Hard switching SMPS topologies for Server and Telecom

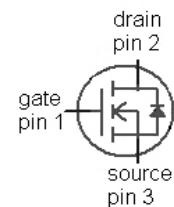
Product Summary

$V_{DS} @ T_{j,max}$	650	V
$R_{DS(on),max}$	0.099	Ω
$Q_{g,typ}$	60	nC

PG-TO247-3-1



Type	Package	Ordering Code	Marking
IPW60R099CP	PG-TO247-3-1	SP000067147	6R099



Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_C=25\text{ °C}$	31	A
		$T_C=100\text{ °C}$	19	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C=25\text{ °C}$	93	
Avalanche energy, single pulse	E_{AS}	$I_D=11\text{ A}$, $V_{DD}=50\text{ V}$	800	mJ
Avalanche energy, repetitive $t_{AR}^{2),3)}$	E_{AR}	$I_D=11\text{ A}$, $V_{DD}=50\text{ V}$	1.2	
Avalanche current, repetitive $t_{AR}^{2),3)}$	I_{AR}		11	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=0\ldots480\text{ V}$	50	V/ns
Gate source voltage	V_{GS}	static	± 20	V
		AC ($f>1\text{ Hz}$)	± 30	
Power dissipation	P_{tot}	$T_C=25\text{ °C}$	255	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
Mounting torque		M3 and M3.5 screws	60	Ncm

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous diode forward current	I_S	$T_C=25\text{ °C}$	18	A
Diode pulse current ²⁾	$I_{S,pulse}$		93	
Reverse diode dv/dt ⁴⁾	dv/dt		15	V/ns

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - case	R_{thJC}		-	-	0.5	K/W
Thermal resistance, junction - ambient	R_{thJA}	leaded	-	-	62	
Soldering temperature, wavesoldering only allowed at leads	T_{solder}	1.6 mm (0.063 in.) from case for 10 s	-	-	260	°C

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$	600	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=1.2\text{ mA}$	2.5	3	3.5	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=600\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$	-	-	5	μA
		$V_{DS}=600\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=150\text{ °C}$	-	50	-	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}$, $I_D=18\text{ A}$, $T_j=25\text{ °C}$	-	0.09	0.099	Ω
		$V_{GS}=10\text{ V}$, $I_D=18\text{ A}$, $T_j=150\text{ °C}$	-	0.24	-	
Gate resistance	R_G	$f=1\text{ MHz}$, open drain	-	1.3	-	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=100\text{ V},$ $f=1\text{ MHz}$	-	2800	-	pF
Output capacitance	C_{oss}		-	130	-	
Effective output capacitance, energy related ⁵⁾	$C_{o(er)}$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}$ to 480 V	-	130	-	
Effective output capacitance, time related ⁶⁾	$C_{o(tr)}$		-	340	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=400\text{ V},$ $V_{GS}=10\text{ V}, I_D=18\text{ A},$ $R_G=3.3\ \Omega$	-	10	-	ns
Rise time	t_r		-	5	-	
Turn-off delay time	$t_{d(off)}$		-	60	-	
Fall time	t_f		-	5	-	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD}=400\text{ V}, I_D=18\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	14	-	nC
Gate to drain charge	Q_{gd}		-	20	-	
Gate charge total	Q_g		-	60	80	
Gate plateau voltage	$V_{plateau}$		-	5.0	-	V

Reverse Diode

Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=18\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.9	1.2	V
Reverse recovery time	t_{rr}	$V_R=400\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	450	-	ns
Reverse recovery charge	Q_{rr}		-	12	-	μC
Peak reverse recovery current	I_{rrm}		-	70	-	A

¹⁾ J-STD20 and JESD22

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Repetitive avalanche causes additional power losses that can be calculated as $P_{AV}=E_{AR} \cdot f$.

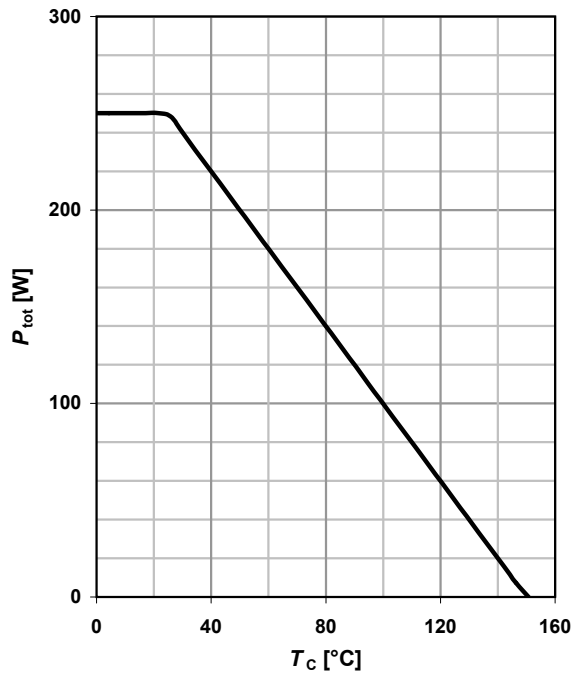
⁴⁾ $I_{SD} \leq I_D$, $di/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DClink}=400\text{ V}$, $V_{peak} < V_{(BR)DSS}$, $T_j < T_{j,max}$, identical low side and high side switch

⁵⁾ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

⁶⁾ $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

1 Power dissipation

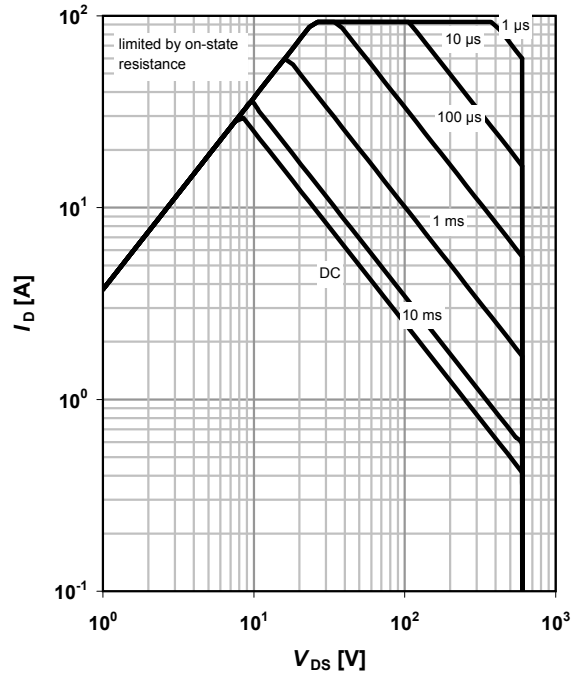
$$P_{\text{tot}} = f(T_C)$$



2 Safe operating area

$$I_D = f(V_{DS}; T_C = 25^\circ\text{C}; D = 0)$$

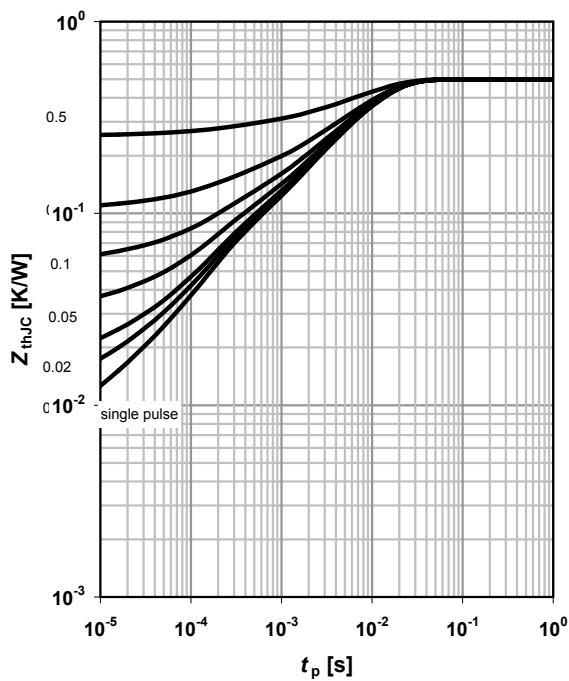
parameter: t_p



3 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

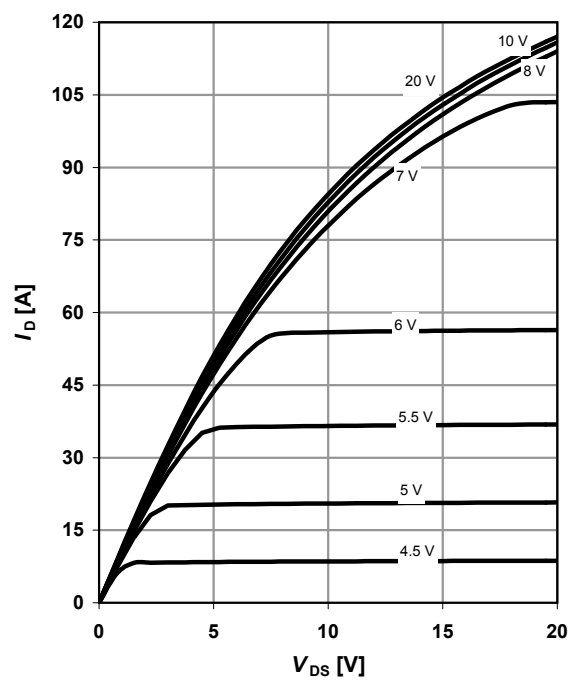
parameter: $D = t_p / T$



4 Typ. output characteristics

$$I_D = f(V_{DS}; T_J = 25^\circ\text{C})$$

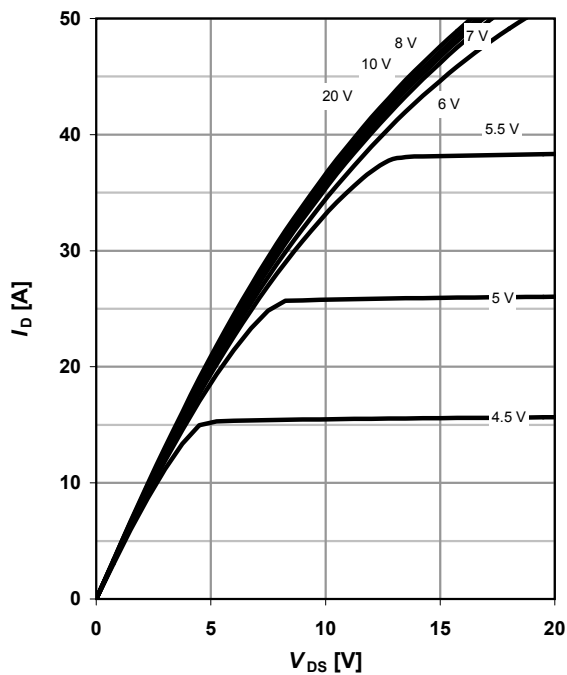
parameter: V_{GS}



5 Typ. output characteristics

$$I_D = f(V_{DS}); T_j = 150^\circ\text{C}$$

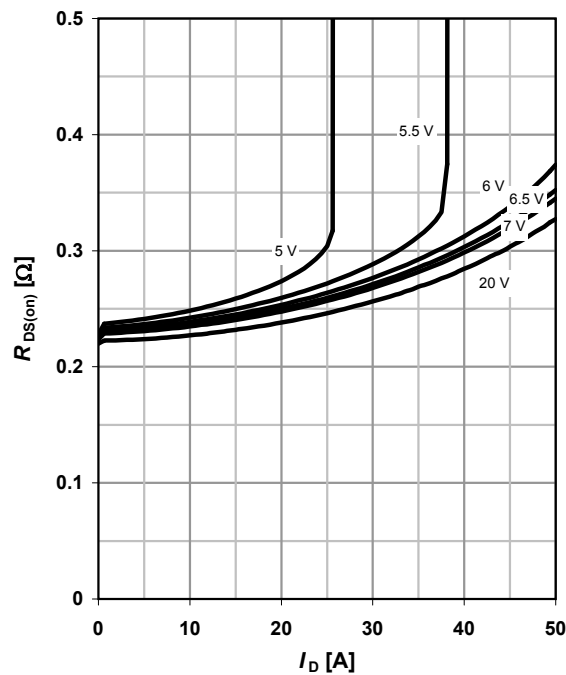
parameter: V_{GS}



6 Typ. drain-source on-state resistance

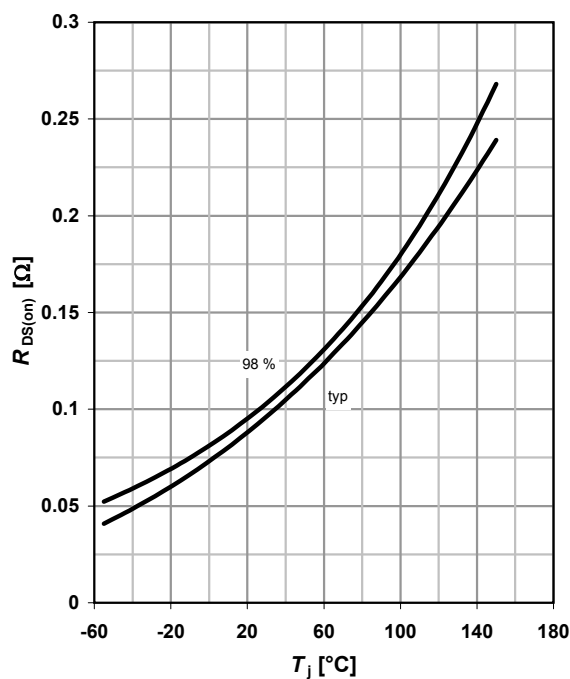
$$R_{DS(on)} = f(I_D); T_j = 150^\circ\text{C}$$

parameter: V_{GS}



7 Drain-source on-state resistance

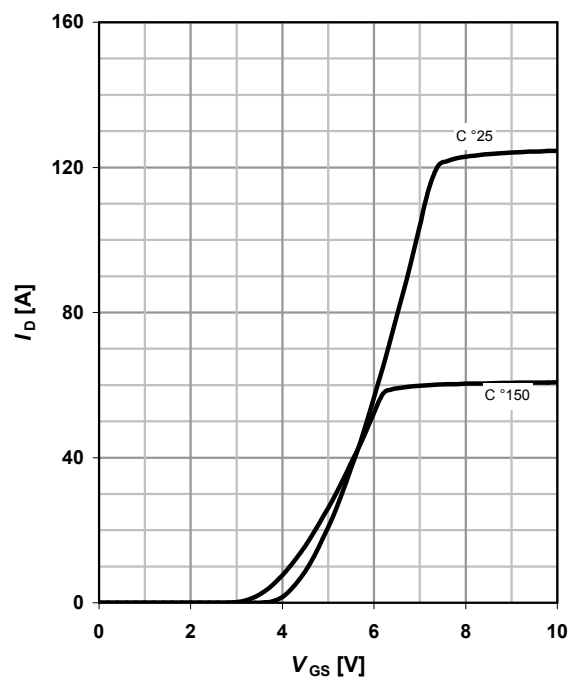
$$R_{DS(on)} = f(T_j); I_D = 18\text{ A}; V_{GS} = 10\text{ V}$$



8 Typ. transfer characteristics

$$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|/R_{DS(on)\max}$$

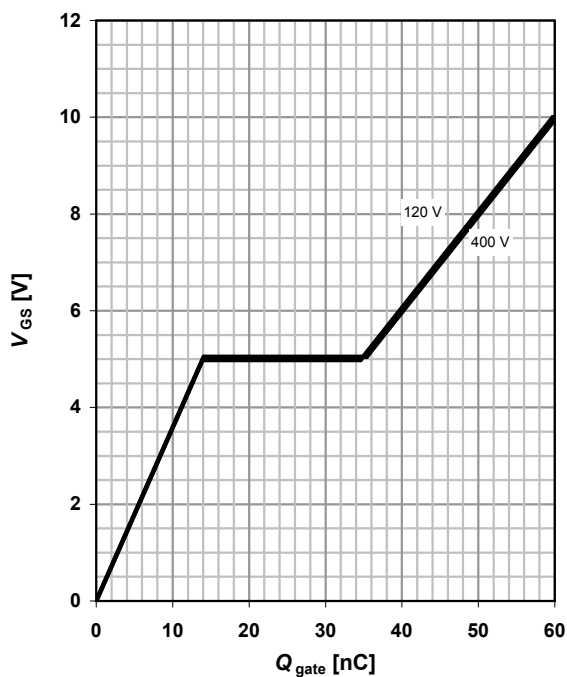
parameter: T_j



9 Typ. gate charge

$$V_{GS}=f(Q_{gate}); I_D=18 \text{ A pulsed}$$

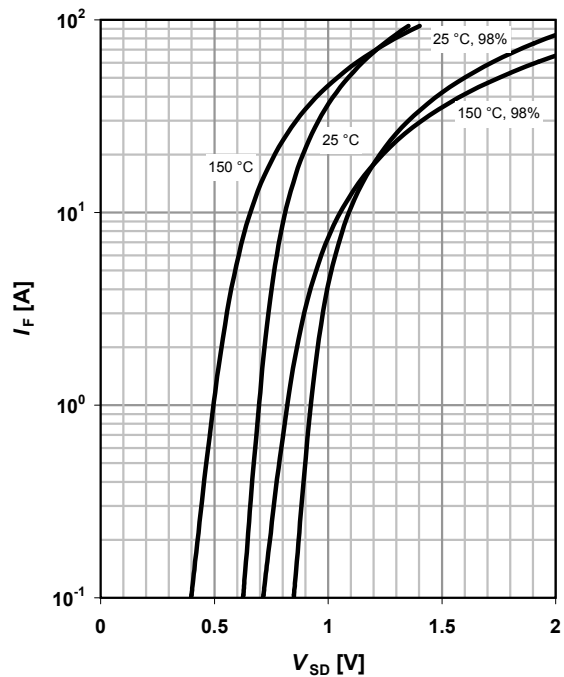
parameter: V_{DD}



10 Forward characteristics of reverse diode

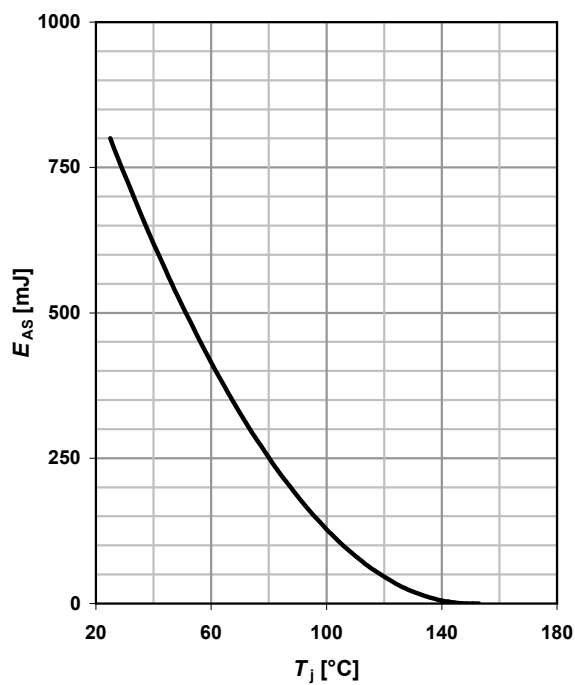
$$I_F=f(V_{SD})$$

parameter: T_j



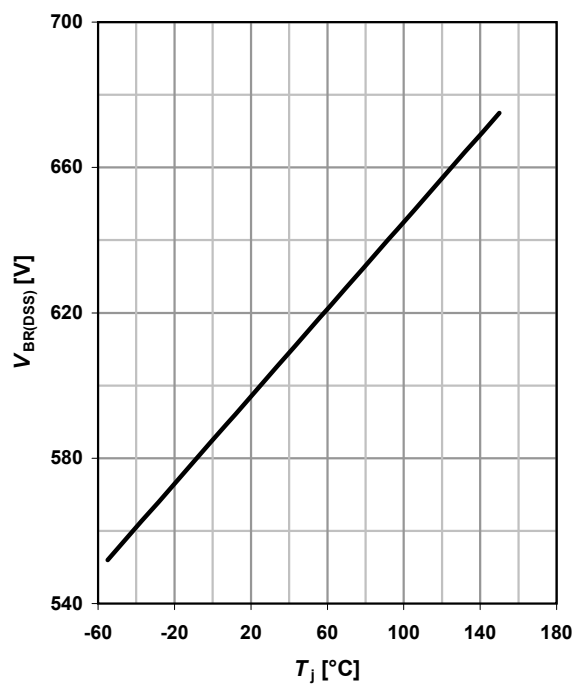
11 Avalanche energy

$$E_{AS}=f(T_j); I_D=11 \text{ A}; V_{DD}=50 \text{ V}$$



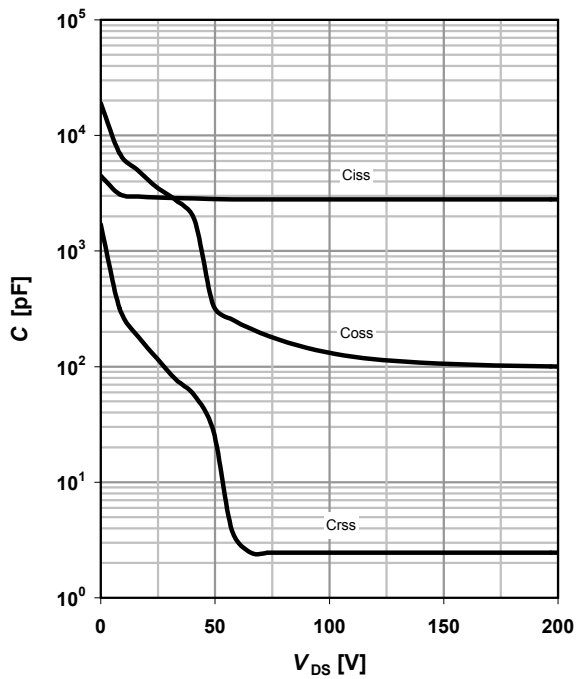
12 Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=0.25 \text{ mA}$$



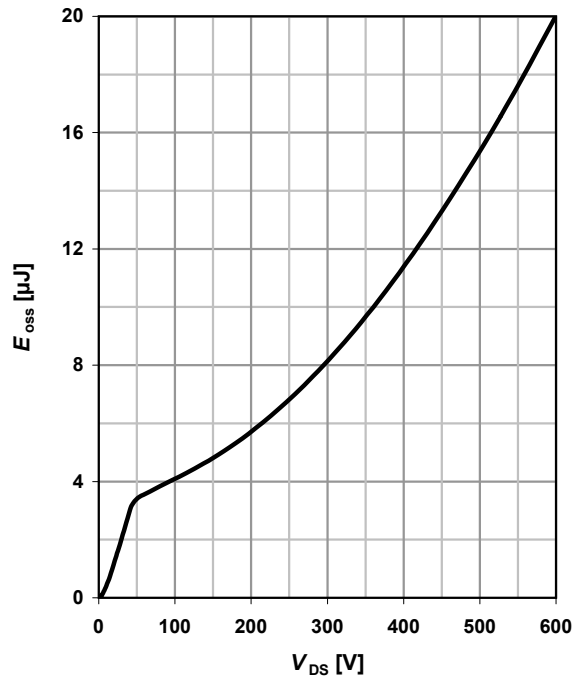
13 Typ. capacitances

$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

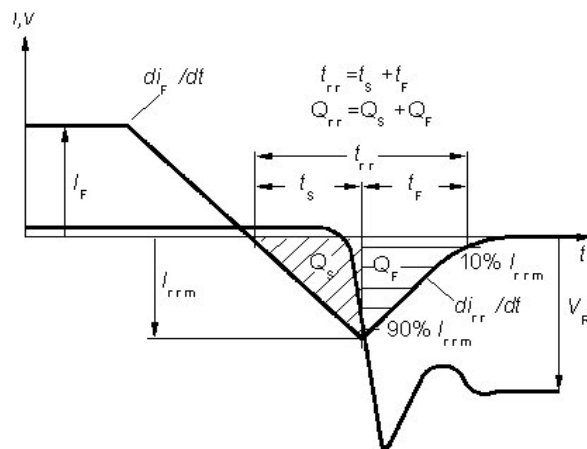


14 Typ. Coss stored energy

$E_{oss} = f(V_{DS})$



Definition of diode switching characteristics



The drawing consists of three views: a front view (top), a top view (bottom), and a side view (right).

Front View (Top): Shows a rectangular part with a central circular hole. Dimensions include overall width E , overall height D , and a distance q from the top edge to the center of the hole. A feature control frame for the hole specifies a diameter of $\phi 0,635$ (M) with a surface texture symbol $\sqrt{\text{A}}$. Other dimensions include $E3$, $E2$, $D2$, $D1$, and $E1$. A section line A-A is indicated.

Top View (Bottom): Shows the plan of the part with dimensions L and $L1$. It includes features $b4$, $b2$, e , and $e1$. A feature control frame for a hole specifies a diameter of $\phi 0,254$ (M) with a surface texture symbol $\sqrt{\text{A}}$. A section line B-B is indicated.

Side View (Right): Shows the profile of the part with dimensions A , $A2$, and c . It includes a section line B-B and a feature control frame for a hole specifying a diameter of $\phi 0,254$ (M) with a surface texture symbol $\sqrt{\text{A}}$.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.903	5.157	0.193	0.203
A1	2.273	2.527	0.092	0.096
A2	1.853	2.107	0.075	0.081
b	1.073	1.327	0.047	0.052
b2	1.903	2.386	0.075	0.094
b4	2.870	3.454	0.113	0.136
c	0.549	0.752	0.024	0.030
D	20.823	21.077	0.820	0.830
D1	17.323	17.831	0.682	0.702
D2	1.063	1.317	0.042	0.052
E	15.773	16.027	0.621	0.631
E1	13.893	14.147	0.547	0.557
E2	3.683	3.937	0.145	0.155
E3	1.683	1.937	0.066	0.076
e	5.450		0.215	
e1	10.900		0.430	
N	3		3	
L	20.053	20.307	0.789	0.799
L1	4.168	4.472	0.164	0.176
øP	3.559	3.661	0.140	0.144
Q	5.493	5.747	0.216	0.226
S	6.043	6.297	0.238	0.248

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